Three International Conferences in One Place

- High Temperature Electronics (HiTEC)
- Ceramic Interconnect & Ceramic Microsystems Tech. (CICMT)
- Advanced Packaging for Power Electronics

A technology crossover event!

April 18-20, 2023  ●  Albuquerque, NM  ●  Marriott Pyramid North

www.imaps.org
The forces behind the International Conferences on High Temperature Electronics (HiTEC), Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT), and Advanced Packaging for Power Electronics have joined for a special co-located technology extravaganza.

All three conferences will be held at the Marriott Pyramid North in Albuquerque, New Mexico from April 18-20, 2023. Each conference will sustain its own unique programming but share common networking and exhibitor functions.
KEY DATES AND LOCATION

Event Dates

April 18-20, 2023
  Conference Programs  April 18-20
  PDCs  April 17
  Exhibition  April 18-19

Event Location & Hotel

Marriott Pyramid North
5151 San Francisco Road NE
Albuquerque, New Mexico USA

How to Book Your Room:
  $179/night + taxes and fees
  Hotel block rates end on April 5th.

For online reservations, visit www.imaps.org
For reservations by phone call 1-888-236-2427.
  Mention IMAPS when booking
**Come for one or come for all!**

Each **attendee** registration includes joint access to all three conference programs, plus the networking and exhibit hall activities for one low price.

Each **exhibitor** registration includes a tabletop in the common networking hall and access to the common event registration list (3 times the reach of our traditional conferences!).

**Sponsorship partners** can choose from function sponsorships, single-conference sponsorships, or a premier multi-conference level of exposure. Each sponsorship includes a tabletop exhibit space in the common networking hall.
HiTEC 2023 continues the tradition of providing the leading biennial conference dedicated to the advancement and dissemination of knowledge of the high temperature electronics industry. Under the organizational sponsorship of the International Microelectronics Assembly and Packaging Society, HiTEC 2023 will be the forum for presenting leading high temperature electronics research results and application requirements. It will also be an opportunity to network with colleagues from around the world working to advance high temperature electronics. Abstracts and exhibitors will be accepted from, but not limited to, the following areas:

**Applications:**
- Geothermal
- Oil well logging
- Automotive
- Military/aerospace
- Space

**Device Technologies:**
- Si, SOI
- SiC
- Diamond
- GaN
- AlN
- Contacts
- Dielectrics

**MEMS and Sensors:**
- Vibration
- Pressure
- Seismic

**Packaging:**
- Materials
- Processing
- Solders/Brazes
- Substrates
- Wire Bonding
- Flip Chip
- Insulation
- Thermal management

**Circuits:**
- Analog
- Digital
- Power
- Wireless
- Mixed Signal

**Energy Sources:**
- Batteries
- Nuclear
- Fuel Cells

**Passives:**
- Resistors
- Inductors
- Capacitors
- Oscillators
- Connectors

**Reliability & Modeling:**
- AI Machine Learning
- Failure mechanisms
- Co-Design
- Prognostics & Health Management
About the 18th International Conference on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT)

The Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT) conference brings together a diverse set of disciplines to share experiences and promote opportunities to accelerate research, development and the application of ceramic interconnect and ceramic microsystems technologies. This international conference features ceramic technology for both microsystems and interconnect applications in the multi-session technical program. The committee is planning sessions and inviting speakers on the following topics:

1. Advanced materials for passive/active devices and their properties
   - Microwave/mm-wave LTCC/ULTCC dielectric materials
   - Ferroelectric/piezoelectric/pyroelectric/ferrite/multiferroic materials
   - Sensitive ceramics/thermoelectric/electrocaloric materials
   - Dielectric/ferroelectric/piezoelectric composites
   - Pastes/inks/slurries for electronics

2. Material processing and device manufacturing technologies
   - LTCC/HTCC and multilayer ceramic and glass processing
   - Emerging ultralow temperature, room temperature processing, and cold sintering processing
   - Additive manufacturing/3D printing/direct writing
   - Advanced thick film processing
   - Thin Film Processing
   - Fine structuring technologies
   - Emerging embedding/integration technologies

3. Devices and Systems for emerging applications
   - Circuits, antennas, and filters for MHz, GHz and THz for communications
   - Automotive/aerospace/medical electronics/optoelectronics
   - Flexible/wearable electronics
   - Sensors and actuators (Integrated physical/chemical/biological)
   - Packaging and integration issues for MEMS and BioMEMS devices
   - Batteries/fuel cells/energy conversion systems
   - Micro-reactors/micro-fluidic devices

4. Design, modeling, simulation, characterization and reliability
   - Metamaterials design, realization and characterization
   - High frequency devices design/modeling/simulation
   - Materials and devices characterization
   - Material and device reliability, lifetime, and failure estimation
   - Thermal management/thermal transfer simulation
About the International Conference on Advanced Packaging for Power Electronics

The Conference on Advanced Packaging for Power Electronics will bring together technologists from a diverse collection of disciplines in power semiconductor packaging, application development, reliability, modeling, process development, thermal management, and advanced materials/manufacturing to support the next generation of power electronics development. The committee is planning sessions and inviting speakers on the following topics:

### POWER PACKAGING TECHNOLOGIES
- Advanced/Sustainable Materials
- Substrates & Module Designs
- Embedding Technologies
- Thermal Management
- Manufacturing Technologies
- Power Interposers
- Additive Manufacturing
- Attachment/Bonding/Joining Technologies
- Planar Interconnects
- Insulation Materials/Strategies

### APPLICATIONS
- Board Mount Power
- Granular Power
- Data Center Power
- Embedded Components
- Integrated Capacitors & Magnetics
- Energy Storage
- Automotive Electronics
- EV Charging
- Power Flip Chip
- Distributed Energy Interfaces

### TOOLS
- Multiphysics Modeling
- Co-Design Simulation
- Characterization Techniques
- Physics of Failure Analysis
- Roadmapping
- Reliability
<table>
<thead>
<tr>
<th>Sponsorship Level</th>
<th>Sponsorship Details</th>
<th>Recognition</th>
<th>Benefits</th>
<th>Cost</th>
<th>Availability</th>
</tr>
</thead>
<tbody>
<tr>
<td>PREMIER SPONSOR</td>
<td>Conference reception -and- Conference lunches (two days)</td>
<td>IMAPS.org sitewide footer ad from March-April 2023</td>
<td>Final program half page ad</td>
<td></td>
<td>$6,000</td>
</tr>
<tr>
<td>HI-TEC SPONSOR</td>
<td>Conference breakfasts and Tuesday breaks (co-sponsorship)</td>
<td>Recognition signage in/near Hi-TEC conference room</td>
<td>One tabletop exhibit space in joint networking hall</td>
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<td>$3,000</td>
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<tr>
<td>CICMT SPONSOR</td>
<td>Conference breakfasts and Tuesday breaks (co-sponsorship)</td>
<td>Recognition signage in CICMT conference room</td>
<td>One tabletop exhibit space in joint networking hall</td>
<td></td>
<td>$3,000</td>
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<tr>
<td>POWER SPONSOR</td>
<td>Conference breakfasts and Tuesday breaks (co-sponsorship)</td>
<td>Recognition signage in Power conference room</td>
<td>One tabletop exhibit space in joint networking hall</td>
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<td>$3,000</td>
</tr>
<tr>
<td>EVENT SPONSOR</td>
<td>Conference breakfasts and Tuesday breaks (co-sponsorship)</td>
<td>Final program half page ad</td>
<td>One (1) complimentary full event registration &amp; 1 exhibit personnel registration</td>
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<td>$1,500</td>
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<tr>
<td>COFFEE BREAK SPONSOR</td>
<td>One networking coffee break (Wed or Thurs – co-sponsorships possible)</td>
<td>Recognition signage during the coffee break</td>
<td>One (1) complimentary full event registration &amp; 1 exhibit personnel registration</td>
<td></td>
<td>$900-$1,150</td>
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<tr>
<td>TABLETOP EXHIBITOR</td>
<td>INCLUDES</td>
<td>RECOGNITION</td>
<td>BENEFITS</td>
<td></td>
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<td></td>
<td>One six-foot table with two chairs and access to electricity</td>
<td>One badge – full OR booth</td>
<td>Discounted full event registrations ($500), booth personnel ($150)</td>
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<tr>
<td></td>
<td>PDF attendee list</td>
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<tr>
<td></td>
<td>Exhibitor listing in program</td>
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</tbody>
</table>
HOW TO COMMIT TO A TABLETOP | Early Registration Discounts End March 24th

Exhibitor Details
Only 30 exhibitor spaces are available! These WILL sell out, so book early!

<table>
<thead>
<tr>
<th>Exhibitor Fees</th>
<th>Member</th>
<th>Non-Member</th>
</tr>
</thead>
<tbody>
<tr>
<td>Early Registration</td>
<td>$900</td>
<td>$1000</td>
</tr>
<tr>
<td>Booked on or before March 24th</td>
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<tr>
<td>Regular Registration</td>
<td>$1050</td>
<td>$1150</td>
</tr>
<tr>
<td>Booked after March 24th</td>
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</tbody>
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How to Register as an Exhibitor

1. Register for a tabletop space or sponsorship online via the conference websites (www.imaps.org).
2. Log into an existing account. New to IMAPS? Create a visitor profile to complete registration.
3. Select the tabletop exhibition option on the registration page.
4. Complete payment.
5. IMAPS staff will instructions months prior to the show for shipping details, badge details, and more.
## HOW TO COMMIT TO A SPONSORSHIP

<table>
<thead>
<tr>
<th>Sponsor Type</th>
<th>Amount</th>
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</thead>
<tbody>
<tr>
<td>Premier Sponsor</td>
<td>$6,000</td>
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<tr>
<td>HiTEC Sponsor</td>
<td>$3,000</td>
</tr>
<tr>
<td>CICMT Sponsor</td>
<td>$3,000</td>
</tr>
<tr>
<td>Power Packaging Sponsor</td>
<td>$3,000</td>
</tr>
<tr>
<td>Coffee Break Sponsor</td>
<td>$1,500</td>
</tr>
</tbody>
</table>

1. Register online for your sponsorship option or contact Brian Schieman, Executive Director, at [bschieman@imaps.org](mailto:bschieman@imaps.org) with your sponsorship selection and questions.
2. You will provide payment in full online or can request an invoice and payment instructions.
3. Email your high-resolution logo file and URL to link to upon commitment to sponsor.
4. Program Ads are due to IMAPS by March 31st.
5. IMAPS staff will contact you several weeks prior to the show to confirm shipping details, request badge details, and more.

Don’t see what you want? All sponsorships can be customized to match your event exposure goals.
HiTEC · CICMT · Power Packaging

www.imaps.org

Contact Us

www.imaps.org
919-293-5000
info@imaps.org

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